
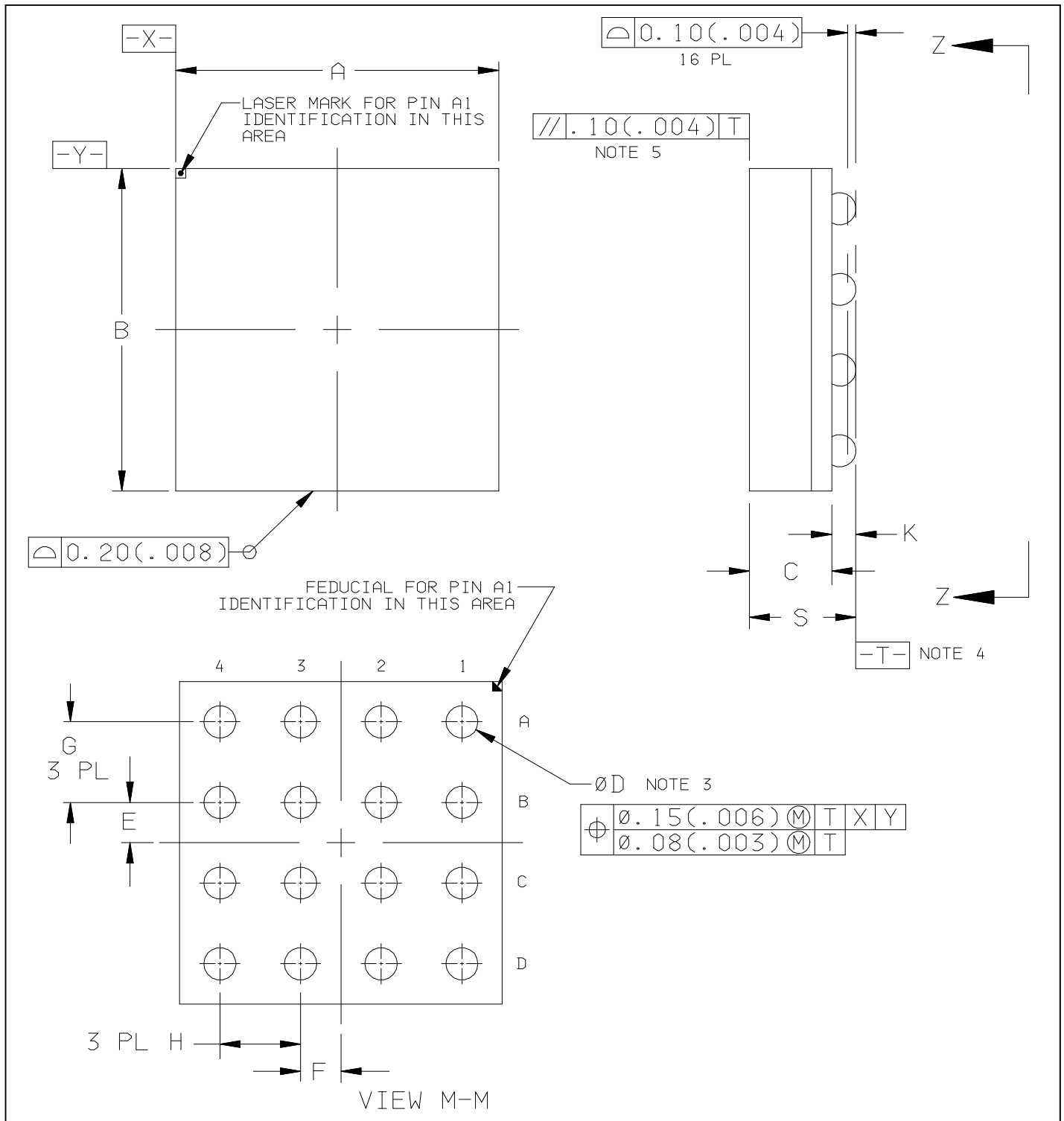



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CASE NO.	489-01
STATUS	ON SEMICONDUCTOR STANDARD
NEW STD	
USED ON	16 PIN FLIP CHIP BGA 4 X 4, 1.0MM PITCH



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NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION D IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL DATUM PLANE -T-.
4. DATUM -T- (SEATING PLANE) IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

DIM	MILLIMETERS		INCHES		DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX		MIN	MAX	MIN	MAX
A	4.00	BSC	0.157	BSC					
B	4.00	BSC	0.157	BSC					
C	1.02	REF	0.040	REF					
D	∅0.30	∅0.50	∅0.012	∅0.020					
E	0.50	BSC	0.020	BSC					
F	0.50	BSC	0.020	BSC					
G	1.00	BSC	0.039	BSC					
H	1.00	BSC	0.039	BSC					
K	0.25	0.35	0.010	0.014					
S	1.40	MAX	0.055	MAX					

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